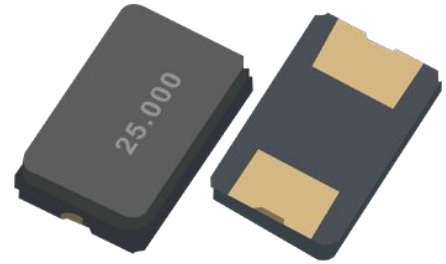


Features

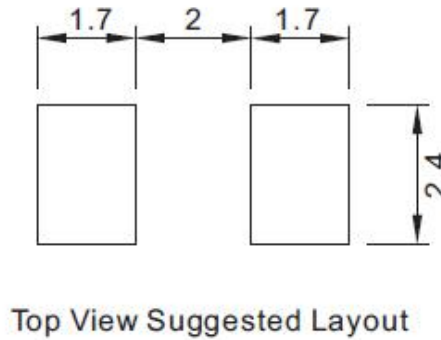
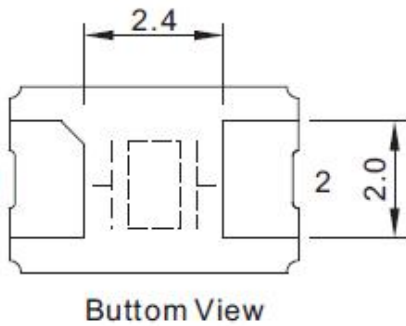
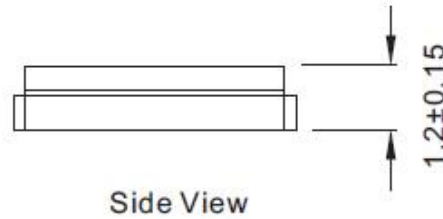
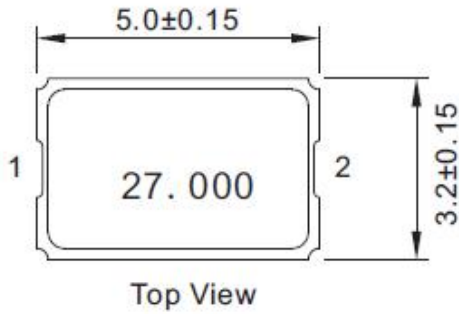
- 5032 size miniature SMD crystal unit with a low profile of 1.2mm
- Wide frequency range from 8MHz to 64MHz
- Excellent heat resistance and environmental characteristics
- High precision and high reliability
- Automatic mounting and reflow soldering
- Reasonable cost and good delivery performance
- Applications: Automotive Applications, GPS, PDA, PC, DSC, USB Interface Card, Multiplayer, AV Equipment, etc



Type	6I Glass Sealed SMD Crystal			
Frequency Range	8~10MHz	10~12MHz	12~40MHz	40~64MHz
Overtone Order	Fundamental			
Load Capacitance	10pF, 16pF, 20pF, or specify			
Drive Level	1~200μW Max. (100μW Typ.)			
Frequency Tolerance (at 25°C)	±10ppm, ±20ppm or specify			
Series Resistance	150Ω Max.	100Ω Max.	50Ω Max.	100Ω Max.
Shunt Capacitance	5pF Max.			
Operating Temperature	-20~+70°C, or specify			
Storage Temperature	-55~+125°C			
Aging (at 25°C)	±3ppm /year Max.			
Packing Unit	1000pcs./Reel			

Standard Specification

Dimensions (mm)



Part ordering information

X	-6I	-25.000	-10	10	50	-C
	Series	Frequency	Load Capacitance	Tolerance	ESR	Temperature Range
		e.g	e.g	e.g	e.g	e.g
		25.000 = 25 MHz	10 = 10pf	10 = 10ppm	50 = 50Ω	A= -10~+60°C B= -20~+70°C C =-40~+85°C D =-40~+105°C E =-55~+125°C

Reliability Tests Specification

Test item	Equipment	Condition	Specification
1.SOLDERABILITY TEST	SJK-REL001、RC-328A	1. Solderability:235±5°C, 5±0.5S 2. Heat resistance:260±5°C,10±1S restoration of 1 hour	MIL-STD-883E Method 2003.7
2. HERMETICITY TEST	HELIOT-306S	FC-84 FLUOROCARBON,BUBBLE MACHINE	MIL-STD-883E Method 1014.10
3. VIBRATION TEST	HG-V4、S&A 250B	Enable Crystal(10g) from 10-55-10Hz,X、Y、Z horizontal,1 Minute vibration/time, 1time/ 2 hours.	MIL-STD-883E Method 2007.3
4.MECHANICAL SHOCK	HPC-200、S&A 250B	Enable Crystal 50G(490m/s2) time=11 ms speed=3.4 m/s half sine wave oscillation	JIS C6701
5. DROP TEST	HARD BOARD.S&A250B	75CM HIGH,3 TIMES ON HARD BOARD	MIL-STD-202F Method 213B
6. HIGH & LOW TEMP STORAGE TEST (Static test)	H-PTH-80CK & HM101-3ABN , S&A 350B/250B	High temperature: 125°C±2°C,1000hr; Low temperature:-40°C±3°C,1000hrs	MIL-STD883C, METHOD 1011.8
7.TEMP & HUM CYCLING TEST	H-PTH-80CK CHAMBE , S&A 350B/250B	Temperature:-10°C±2°C~65°C±2°C,Humidity:93±3%,1 cycle need 24 hrs. 5cycles.	MIL-STD-883E Method 1005.8
8. HIGH TEM. & HUM. STORAGE TEST	H-PTH-80CK CHAMBE , S&A 350B/250B	Temperature:40°C±2 , Humidity:85+3,- 2%,Store 96 hrs	JIS C6701
9.AGEING TEST	H-PTH-80CK CHAMBE , S&A 350B/250B	Temperature:40°C±2 , Humidity:85+3,- 2%,Store 96 hrs	JIS C5023



X-6I Series
Glass Sealed SMD Crystal
Size: 5032 (5.0×3.2×1.2mm)
8~64 MHz / 10~20 pF / 10~20ppm

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